

Manual wire bonder

Manufacturer: Kulike & Soffa

Model: K&S 4526



General Description:

With the manual wire bonder, contacts can be established between chip bond pads and adjacent contact pads, e.g. from a housing in which the chip has been placed or from a printed circuit board on which the chip has been fixed onto. The machine can be equipped with different bonding wires like aluminum, gold or platinum.

Key Specifications:

- Default bonding wire: 25µm Aluminum
- Bondhead linear Z travel: 60mm
- Manipulator in X and Y: 18x18mm
- Various mounting options for sample holder. Usually with mechanical clamping or vacuum
- Substrate Size: up to 4 inch
- Heated chuck allows for bonding procedures at elevated temperatures

Availability:

Use allowed for all researchers with permission

Location

Cleanroom C8
 Europastraße 12
 9524 Villach

Responsibles / Contact

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